

# New Generation of Board & Packaging Forming Fabrics MultiForm IC

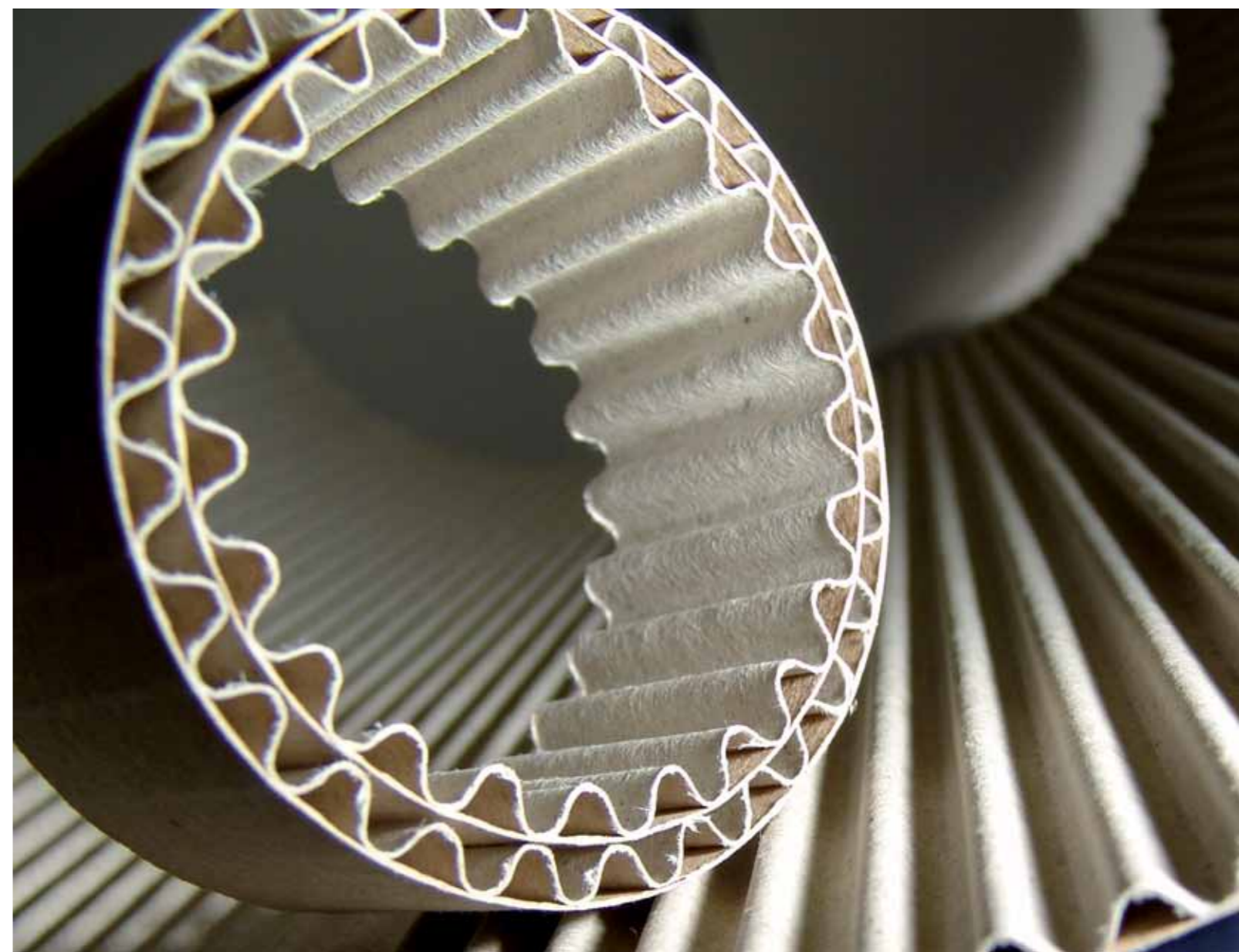
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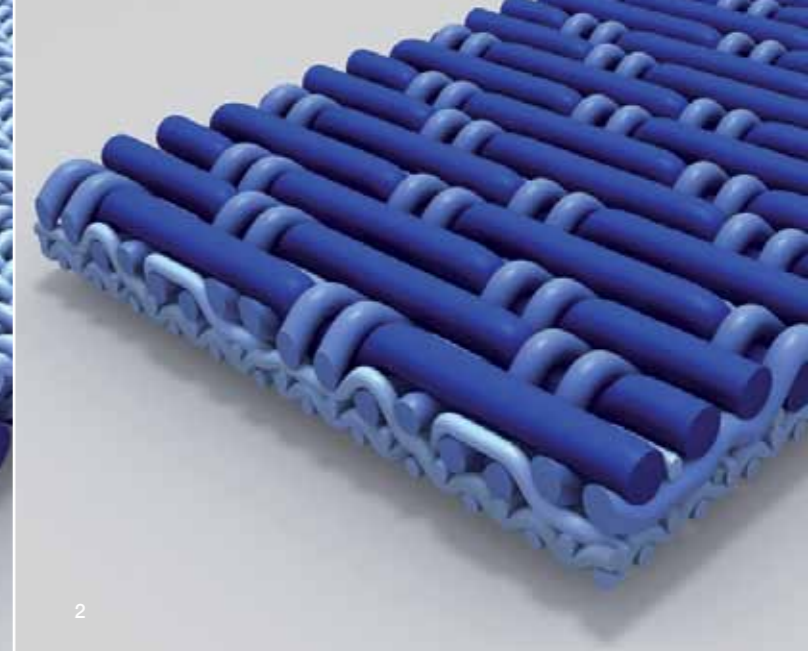
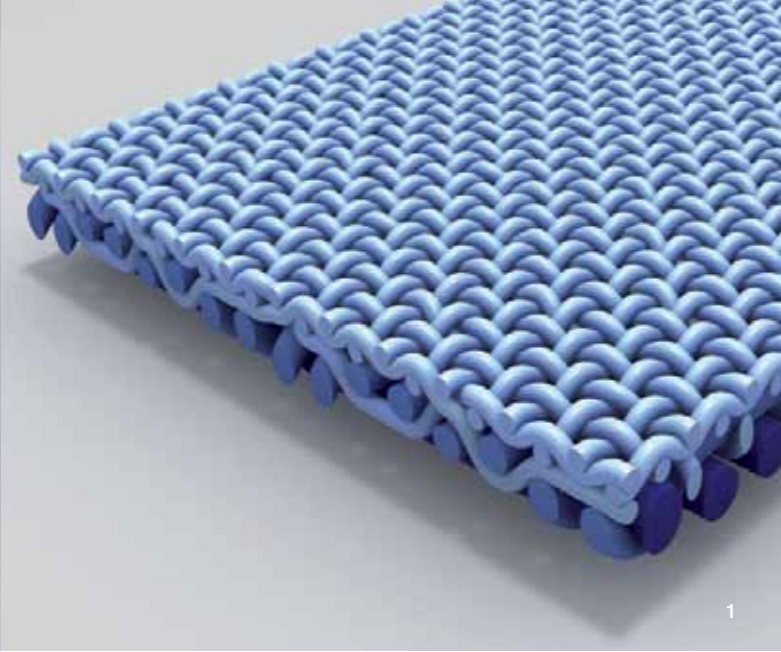
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## New Forming Fabric for demanding Board & Packaging applications

MultiForm IC is the latest development in the Voith family of I-Series products, designed specifically for the most demanding Board & Packaging applications and furnishes. It features a combination of superior drainage, durability and fiber support over previous generations of SSB fabric designs. The very stiff MultiForm IC especially for Board & Packaging applications provides excellent retention, stability and life potential properties.

The I-Series utilizes a completely new and proprietary SSB design concept to generate a fabric with a much wider range of operating features, offering today's papermaker improved overall performance and optimal cost efficiencies.



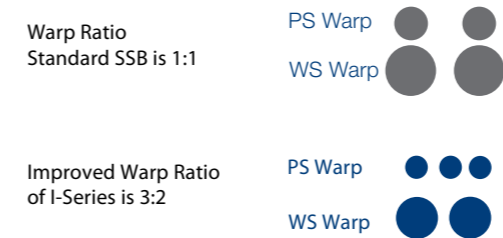
1 Top Side MultiForm IC  
2 Bottom Side MultiForm IC

## Improved SSB Design – MultiForm IC

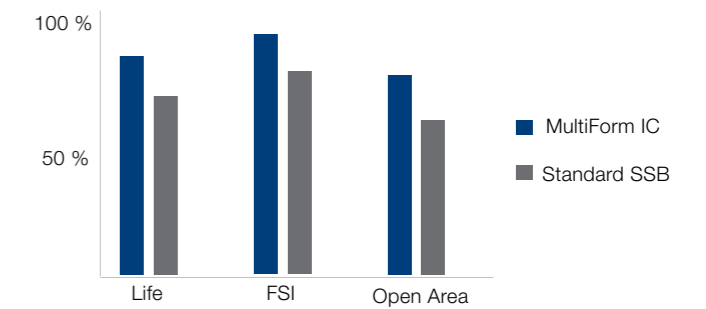
MultiForm IC takes the Sheet Support Binder concept to the next level of performance.

### The warp concept

The unique 3 over 2 warp setup allows for industry high open area and fiber support values in the same fabric; along with superior wear volumes and stability at competitive calipers. All areas of fabric performance are optimized in MultiForm IC, there is no longer any need to ask the papermaker to sacrifice in one area of performance to optimize another. MultiForm IC is the most complete fabric design on the market.



Warp Ratio Comparison



Comparison Standard SSB and MultiForm IC



## New Forming Fabric for demanding Board & Packaging applications

Proven advantages with MultiForm IC

- Improved drainage
- Reduced fiber bleed
- Optimal retention
- Record life potential
- Reduced drive loads

# MultiForm IC meets a wider range of paper-making needs for Board & Packaging applications

Board & Packaging fabric application consists of finding the right balance of fabric properties and features that best fits each individual application. With previous generations of SSB designs, this has often involved trade-offs. The new MultiForm IC meets a wider range of application needs.



3 Corrugated Medium  
4 Linerboard Paper

### Drainage and Fiber Support

In today's Board & Packaging environment, the demands for increased use of cheaper waste furnish – with associated shorter fiber – and increased couch solids and machine speeds require a high performance forming fabric.

Fabrics need to be more open to handle the demands of slower dewatering furnishes and increased speeds, but they also need to have finer papermaking surfaces to achieve retention and fiber bleed expectations.

The unique warp structure of MultiForm IC allows for industry high open area and fiber support values in the same fabric. Drainage, couch solids, retention, fiber bleed, sheet release and draws are all optimized with MultiForm IC.

### Wear potential, stability, caliper and drive loads

The warp construction and wear surface of MultiForm IC generate industry high wear volumes, while maintaining a very open structure for drainage and at calipers at competitive levels for any given wear yarn diameter.

MultiForm IC has run with significantly reduced drive loads against existing SSB products on a number of demanding applications, while setting life records. The open structure of MultiForm IC also is ideally suited for waste furnishes with high stickie loads, allowing easier shower penetration for ease of cleaning.

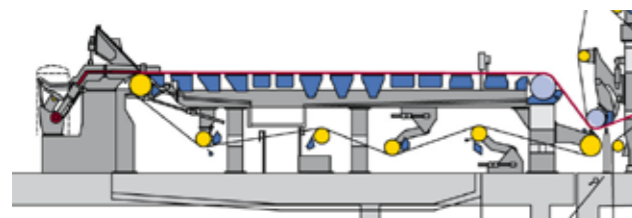


5 Corrugated Medium  
6 Multilayer Machine

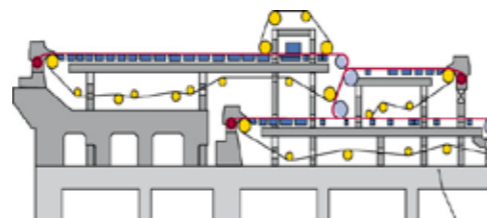


**Fourdrinier and Hybrid Top formers**

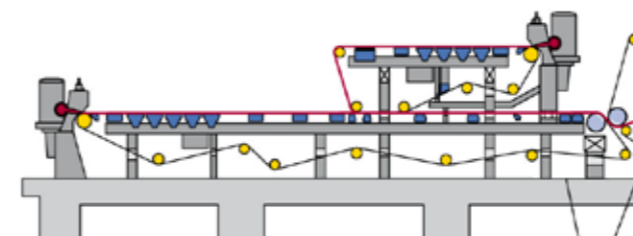
- Improved drainage over existing SSB designs
- Higher headbox flows where fan pump capacities allow
- Increased refining while maintaining drainage and couch solids
- Excellent retention, minimal fiber bleed
- Improved sheet release
- Increased wear volumes – record life potential
- Extreme stability – minimal MD stretch, CD narrow, or fabric skew.
- Very guide stable under stock-on stock-off conditions
- Flat edges prevent interference with steam hoods
- Reduced drive loads over existing SSB designs
- Open warp structure and ease of cleaning result in optimal showering efficiencies
- Competitive calipers for critical applications



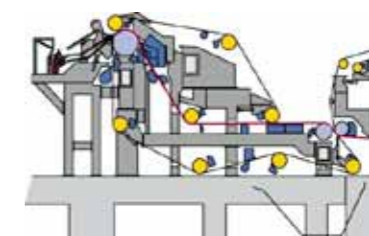
Fourdrinier Machine



Multilayer Machine with three Headboxes



Multilayer Machine with two Headboxes



Gapformer Machine

**Fourdrinier, Base Positions on Multitable and Hybrid Former Units**

- Papermaking surface of MultiForm IC is fine enough to make lightweight cover ply on many applications
- Papermaking surface fine enough to eliminate fiber carry and spray from demanding hybrid top units
- Fine mesh design with highest life potential
- Produced down to 400cfm for select MiniTop applications
- Extreme width and skew stability for hybrid top units where alignment may be less than ideal (BelBonds)

**Gapformer Machines**

- Extreme width/skew stability and CD bending stiffness
- Very stable platform for jet delivery
- Minimize power fingering and ridging
- Very high drainage capacities with industry high open areas
- Ideally suited for formers with short drainage zones
- High fiber support prevents bleed or poor retention
- Record life potential
- Significantly increase wear volumes for any given wear yarn diameter and fabric caliper
- MultiForm IC with large 0.50 mm wear yarn has a caliper of 0.050" / 1,3 mm
- Reduced cost of operation
- Reduced drive loads over existing SSB designs, with the wear volumes needed to establish record lives
- Industry fine papermaking surface optimizes retention levels
- Industry fine top surface and high drainage capacity result in optimal draws
- Open warp structure and ease of cleaning result in optimal showering efficiencies